

Epoxy Conductive Adhesive DT1204

Description:

LEED epoxy conductive adhesive is organic synthesis by high viscosity epoxy glue and high conductive silver. It is an environmental non-toxic element up to European ENIASIM & GB standard, and it is perfect felted product on surface between various hard metal between matt surface and metalloid surface. This product can splice different electronic elements, also between conductive ceramics and microwave components instead of soldering tin. It designed on aerospace, microwave, radar, computer, consumer electronic ext.

Data sheet

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Silver Content (%)	78%±2
Viscosity (Pa·S) (Brookfield HBT, 25°C, 10rpm)	12~20 Pa·S
Propotion	3.4±0.3
Fineness	≤10um
Thixotropy index	6.0~7.5
Drying	130°C/60min,150°C/30min,170°C/10min
Shear strength	≥40N
Resistivity	$\leq 0.5 \times 10^{-3} \Omega \cdot \text{cm}$
Coefficient of thermal conductivity (120°C)	1.2~6.5W/m°CK
Modulus	250~350Mpa
Ionized impurities after gekocht	Cl ⁻ ≤5ppm Na ⁺ ≤5ppm K ⁺ ≤3ppm
Package	1KG/pot
Shelf Life(≤0°C)	6 months

Notice of Usage And Storage

- 1. Data in the table are measured under the specific conditions and do not represent the specifications.
- 2. Viscosity can be adjusted according to customer requirements and it only to meet the printing requirement.
- 3. The purpose to add thinner is to make up for long-term preservation volatile organic carrier case, under normal circumstances is not recommended to add.
- 4. Automatic dispensing or screen printing: not less than 10,000 cleanliness in the construction of the clean shop, clean room ventilation, ambient temperature 24 $\hat{A}\pm2~\hat{a}~$, after the gum or glue, must be done in 1 hour to avoid the loss of adhesion.
- 5. Mixing: Stir about 5 minutes, stirring clockwise direction, the speed can not be too fast to avoid the accelerated hardening. Use immediately after mixing (gum or glue), the unused paste, please immediately into the freezer within 1 hour.